



SULIT & PERSENDIRIAN

27 September 2022

MUFG Bank (Malaysia) Berhad
Level 9, Menara IMC,
No. 8, Jalan Sultan Ismail,
50250 Kuala Lumpur

HSBC Bank Malaysia Berhad
(Company No. 198401015221 (127776-V))

Menara IQ
Lingkaran TRX
55188 Tun Razak Exchange
Kuala Lumpur, Malaysia

T. 03 2075 3000
www.hsbc.com.my

Dear Sir / Madam

HSBC Bank Malaysia Berhad ("HBMY") - Redemption of MYR500m Tier 2 Subordinated-Bond ("Sub-Bond")

1. Background

HBMY issued a MYR500 million Tier 2 Sub-Bond in 2007 to external institutional investors. Based on the principal terms and conditions of the issuance, the Sub-Bond's first call date is on 2 November 2022.

The details of the Sub-Bond are as follows:-

Issue Size:	MYR500 million
Tenor:	20 years from issue date on a 20 non-callable 15 basis
Maturity Date:	2 November 2027
First Redemption (Call) Date:	2 November 2022
Coupon Rate:	5.05% p.a. with interest step up of 6.05% p.a. after first redemption date

2. Notice

The purpose of this letter is to notify that HBMY is exercising early redemption in accordance to Clause 6.5 to redeem the full issue size of the above Sub-Bond on the first Call Date (i.e. 2 November 2022) at the nominal value of the Sub-Bond together with all accrued interest (if any).

We wish to confirm that we have also obtained BNM's approval for the redemption of the above Sub-Bond.

Please do not hesitate to contact Estee Lau at 03-2075 3278 (email: esteelau@hsbc.com.my) for any clarification required.

Thank you.

Your faithfully,

Dato' Omar Siddiq

Chief Executive Officer, HSBC Bank Malaysia Berhad